

**In the United States Patent and Trademark Office**

Serial Number:	10/760246		
Application. Filed:	January 21, 2004		
Applicant:	Kia Silverbrook; Norman Micheal Berry; Garry Raymond Jackson; Akira Nakazawa		
Application Title:	Printhead Assembly with Interconnected Printhead Modules		
Examiner/GAU:	Laura E Martin	2853	
	Dated	March 23, 2007	
	At:	Balmain, NSW	
	Docket No.	MPA10US	

**REPLY**

Commissioner for Patents  
Washington, District of Columbia 20231

Dear Sir:

Applicant thanks Examiner for the detailed Office Action dated January 19, 2007. In response to the issues raised, the Applicant offers the following submissions.

**35 U.S.C. §103 - Claims 1 and 5**

Claims 1 and 5 stand rejected as obvious in light of US 6,439,908 to Silverbrook et al in view of US application 2002/0180834 to Silverbrook. The Applicant disagrees as the citations do not disclose all the elements of claim 1, and hence claim 5.

Claim 1 is restricted to a printhead assembly that has two or more printhead modules. Each printhead module has a plurality of printhead ICs fixedly mounted to a support member. The Examiner equates the printhead assembly 10 of '908 with the printhead module and the ink reservoir molding 32 with the support member. The printhead assembly 10 has a plurality of printhead ICs 18, however, these are individually fixed to the detachable modules 12.

The Examiner argues that the printhead ICs 18 are fixedly mounted to the support member 32 via the ink connectors 40. The Applicant respectfully disagrees. The replaceable printhead modules 12 are configured to be user detachable (see col.2, lines 1-5 of '908). The soft elastomeric collars 40 form an ink seal with the ink funnels 38 on each module 12. They do not fixedly mount the modules to the ink reservoir molding 32 (equated to the support member).

The Examiner has equated the busbar contacts 56 in '908 with the casing that removably mounts the modules in linear alignment. As the contacts 56 connect with only one printhead module (printhead assembly 10), there is no disclosure of two or more modules (printhead assemblies 10) removably mounted on the contacts 10 in linear alignment. This is an essential element of claim 1.

The Examiner contends that '834 teaches linearly aligned modules with fluid interconnection. Again we respectfully disagree. The '834 wide format printer design uses a plurality of ink reservoir moldings 74 as part of the printheads ink distribution arrangement 72. These moldings do not have a plurality of printhead ICs mounted to a support member. The '834 printhead modules 46 each have a single printhead IC 186 and they are removably mounted to the ink distribution system 72. Therefore, '834 does not disclose modules, as defined by claim 1, which are mounted in linear alignment and fluidly interconnected.

Accordingly, the cited reference does not teach all the elements of claim 1 or claim 5.

### **35 U.S.C. §103 – Claim 2**

Claim 2 stands rejected as obvious in light of US 6,439,908 to Silverbrook in view of US 5,658,158 to Milan.

As discussed above, '908 fails to disclose several elements defined in claim 1. The disclosure in Milan also fails to teach or suggest these elements. As claim 2 incorporates these elements by virtue of its indirect dependence from claim 1, it is clear that the citations fail to support a rejection on the basis of §103.

### **35 U.S.C. §103 – Claim 3 and 4**

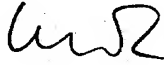
Claims 3 and 4 stand rejected as obvious in light of US 6,439,908 to Silverbrook and US application 2002/0180834 to Silverbrook, in view of US 5,658,158 to Milan and US 6,180,002 to Higgins.

As discussed above, '908 and Milan fail to teach or suggest several elements defined in claim 2. The disclosures in Higgins and '834 also fail to teach or suggest these elements. As claims 3 and 4 incorporate these elements by virtue of its indirect dependence from claim 2, it is clear that the citations fail to support a rejection on the basis of §103.

It is respectfully submitted that the Examiner's rejections have been successfully traversed and the application is now in condition for allowance. Accordingly, favorable reconsideration is courteously solicited.


Very respectfully,

Applicants:



---

Kia Silverbrook



---

Norman Micheal Berry



---

Garry Raymond Jackson



---

Akira Nakazawa

C/o: Silverbrook Research Pty Ltd  
393 Darling Street  
Balmain NSW 2041, Australia

Email: [kia.silverbrook@silverbrookresearch.com](mailto:kia.silverbrook@silverbrookresearch.com)

Telephone: +612 9818 6633

Facsimile: +61 2 9555 7762